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13-BIT TO 26-BIT REGISTERED BUFFER WITH SSTL I/O

IDT74SSTVN16859

FEATURES:

- 1:2 registered output buffer
- 2.3V to 2.7V operation for PC1600, PC2100, and PC2700
- 2.5V to 2.7V operation for PC3200
- Single bit propagation delay, TSSOP : 2.2ns, VFQFPN : 1.8ns
- SSTL_2 Class I style data inputs/outputs
- Differential CLK input
- $\overline{\text{RESET}}$ control compatible with LVCMOS levels
- Latch-up performance exceeds 100mA
- ESD >2000V per MIL-STD-883, Method 3015; >200V using machine model (C = 200pF, R = 0)
- Available in 56 pin VFQFPN and 64 pin TSSOP packages

APPLICATIONS:

- Ideally suited for stacked DIMM DDR registered applications
- Along with CSPT857C/D, Zero Delay PLL Clock buffer, provides complete solution for DDR1 DIMMs

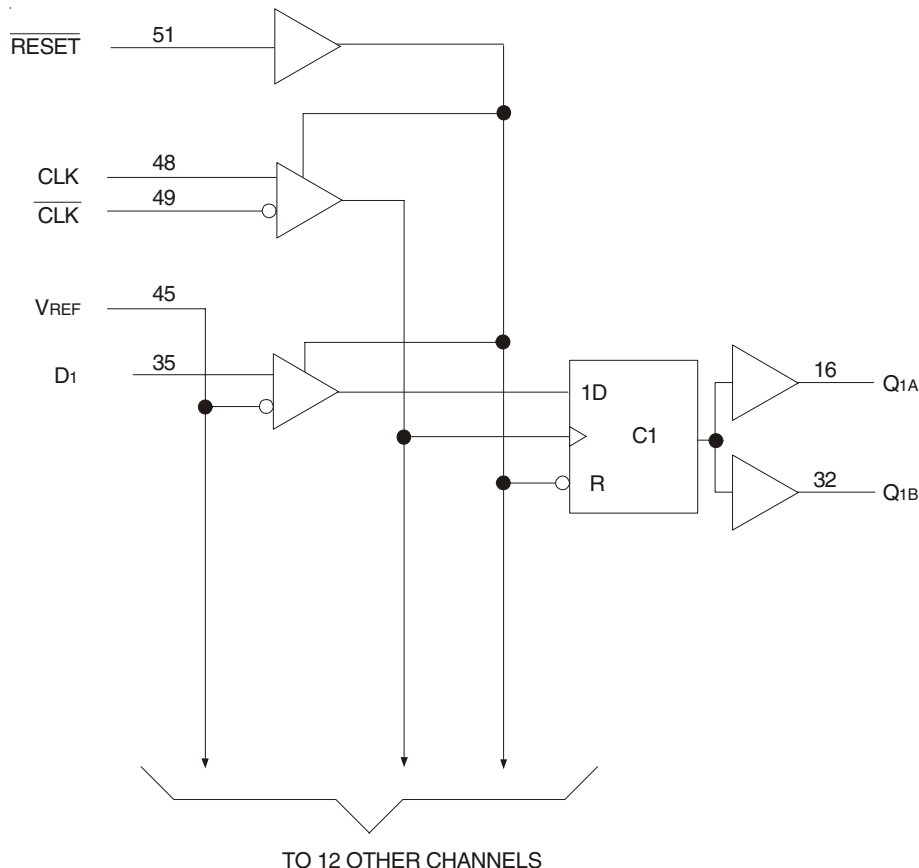
DESCRIPTION:

The SSTVN16859 is a 13-bit to 26-bit registered buffer designed for 2.3V-2.7V V_{DD} for PC1600 - PC2700 and 2.5V-2.7V V_{DD} for PC3200, and supports low standby operation. All data inputs and outputs are SSTL_2 level compatible with JEDEC standard for SSTL_2.

$\overline{\text{RESET}}$ is an LVCMOS input since it must operate predictably during the power-up phase. $\overline{\text{RESET}}$, which can be operated independent of CLK and $\overline{\text{CLK}}$, must be held in the low state during power-up in order to ensure predictable outputs (low state) before a stable clock has been applied.

$\overline{\text{RESET}}$, when in the low state, will disable all input receivers, reset all registers, and force all outputs to a low state, before a stable clock has been applied. With inputs held low and a stable clock applied, outputs will remain low during the Low-to-High transition of $\overline{\text{RESET}}$.

FUNCTIONAL BLOCK DIAGRAM



PIN DESCRIPTION

Pin Names	Description
Q1 - Q13	Data Output
GND	Ground
V _{DDQ}	Output-stage drain power voltage
V _{DD}	Logic power voltage
$\overline{\text{RESET}}$	Asynchronous reset input - resets registers and disables data and clock differential input receivers
V _{REF}	Input reference voltage
CLK	Positive master clock input
$\overline{\text{CLK}}$	Negative master clock input
D1 - D13	Data Input - clocked in on the crossing of the rising edge of CLK and the falling edge of $\overline{\text{CLK}}$
Center PAD	Ground (MLF package only)

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE FOR PC1600 - PC2700

Following Conditions Apply Unless Otherwise Specified:

Operating Condition: T_A = 0°C to +70°C, V_{DD} = 2.5V ± 0.2V, V_{DDQ} = 2.5V ± 0.2V

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{IK}	Control Inputs	V _{DD} = 2.3V, I _I = -18mA	—	—	-1.2	V
V _{OH}		V _{DD} = 2.3V to 2.7V, I _{OH} = -100μA	V _{DD} - 0.2	—	—	V
		V _{DD} = 2.3V, I _{OH} = -8mA	1.95	—	—	
V _{OL}		V _{DD} = 2.3V to 2.7V, I _{OL} = 100μA	—	—	0.2	V
		V _{DD} = 2.3V, I _{OL} = 8mA	—	—	0.35	
I _I	All Inputs	V _{DD} = 2.7V, V _I = V _{DD} or GND	—	—	±5	μA
I _{DD}	Static Standby	I _O = 0, V _{DD} = 2.7V, $\overline{\text{RESET}}$ = GND	—	—	0.01	mA
	Static Operating	I _O = 0, V _{DD} = 2.7V, $\overline{\text{RESET}}$ = V _{DD} , V _I = V _{IH} (AC) or V _{IL} (AC)	—	—	20	
I _{DDQ}	Dynamic Operating (Clock Only)	I _O = 0, V _{DD} = 2.7V, $\overline{\text{RESET}}$ = V _{DD} , V _I = V _{IH} (AC) or V _{IL} (AC), CLK and $\overline{\text{CLK}}$ Switching 50% Duty Cycle.	—	6	—	μA/Clock MHz
	Dynamic Operating (Per Each Data Input) ⁽¹⁾	I _O = 0, V _{DD} = 2.7V, $\overline{\text{RESET}}$ = V _{DD} , V _I = V _{IH} (AC) or V _{IL} (AC), CLK and $\overline{\text{CLK}}$ Switching 50% Duty Cycle. One Data Input Switching at Half Clock Frequency, 50% Duty Cycle.	—	43	—	μA/Clock MHz/Data Input
C _I	Data Inputs	V _{DD} = 2.5V, V _I = V _{REF} ± 310mV	2	—	3	pF
	CLK and $\overline{\text{CLK}}$	V _{ICR} = 1.25V, V _I (PP) = 360mV	2	—	3	
	$\overline{\text{RESET}}$	V _I = V _{DD} or GND	2	—	3	

NOTE:

- Power dissipation levels will allow operation at DDR333 speeds without excessive die temperature.

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE FOR PC3200

Following Conditions Apply Unless Otherwise Specified:

Operating Condition: $T_A = 0^\circ\text{C}$ to $+70^\circ\text{C}$, $V_{DD} = 2.6\text{V} \pm 0.1\text{V}$, $V_{DDQ} = 2.6\text{V} \pm 0.1\text{V}$

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_{IK}	Control Inputs	$V_{DD} = 2.5\text{V}$, $I_i = -18\text{mA}$	—	—	-1.2	V
V_{OH}		$V_{DD} = 2.5\text{V}$ to 2.7V , $I_{OH} = -100\mu\text{A}$	$V_{DD} - 0.2$	—	—	V
		$V_{DD} = 2.5\text{V}$, $I_{OH} = -8\text{mA}$	1.95	—	—	
V_{OL}		$V_{DD} = 2.5\text{V}$ to 2.7V , $I_{OL} = 100\mu\text{A}$	—	—	0.2	V
		$V_{DD} = 2.5\text{V}$, $I_{OL} = 8\text{mA}$	—	—	0.35	
I_i	All Inputs	$V_{DD} = 2.7\text{V}$, $V_i = V_{DD}$ or GND	—	—	± 5	μA
I_{DD}	Static Standby	$I_o = 0$, $V_{DD} = 2.7\text{V}$, $\overline{\text{RESET}} = \text{GND}$	—	—	0.01	mA
	Static Operating	$I_o = 0$, $V_{DD} = 2.7\text{V}$, $\overline{\text{RESET}} = V_{DD}$, $V_i = V_{IH}(\text{AC})$ or $V_{IL}(\text{AC})$	—	—	20	
I_{DD}	Dynamic Operating (Clock Only)	$I_o = 0$, $V_{DD} = 2.7\text{V}$, $\overline{\text{RESET}} = V_{DD}$, $V_i = V_{IH}(\text{AC})$ or $V_{IL}(\text{AC})$, CLK and $\overline{\text{CLK}}$ Switching 50% Duty Cycle.	—	6	—	$\mu\text{A}/\text{Clock}$ MHz
	Dynamic Operating (Per Each Data Input) ⁽¹⁾	$I_o = 0$, $V_{DD} = 2.7\text{V}$, $\overline{\text{RESET}} = V_{DD}$, $V_i = V_{IH}(\text{AC})$ or $V_{IL}(\text{AC})$, CLK and $\overline{\text{CLK}}$ Switching 50% Duty Cycle. One Data Input Switching at Half Clock Frequency, 50% Duty Cycle.	—	43	—	
C_i	Data Inputs	$V_{DD} = 2.6\text{V}$, $V_i = V_{REF} \pm 310\text{mV}$	2	—	3	pF
	CLK and $\overline{\text{CLK}}$	$V_{ICR} = 1.3\text{V}$, $V_i(\text{PP}) = 360\text{mV}$	2	—	3	
	$\overline{\text{RESET}}$	$V_i = V_{DD}$ or GND	2	—	3	

NOTE:

- Power dissipation levels will allow operation at DDR400 speeds without excessive die temperature.

OPERATING CHARACTERISTICS, $T_A = 25^\circ\text{C}$ (1)

Symbol	Parameter		Min.	Typ. ⁽¹⁾	Max.	Unit
V_{DD}	Supply Voltage		V_{DDQ}	—	2.7	V
V_{DDQ}	Output Supply Voltage	PC1600 - PC12700	2.3	2.5	2.7	V
		PC3200	2.5	2.6	2.7	
V_{REF}	Reference Voltage ($V_{REF} = V_{DDQ}/2$)	PC1600 - PC2700	1.15	1.25	1.35	V
		PC3200	1.25	1.3	1.35	
V_{TT}	Termination Voltage		$V_{REF} - 40\text{mV}$	V_{REF}	$V_{REF} + 40\text{mV}$	V
V_i	Input Voltage		0	—	V_{DD}	V
V_{IH}	AC High-Level Input Voltage	Data Inputs	$V_{REF} + 310\text{mV}$	—	—	V
V_{IL}	AC Low-Level Input Voltage	Data Inputs	—	—	$V_{REF} - 310\text{mV}$	V
V_{IH}	DC High-Level Input Voltage	Data Inputs	$V_{REF} + 150\text{mV}$	—	—	V
V_{IL}	DC Low-Level Input Voltage	Data Inputs	—	—	$V_{REF} - 150\text{mV}$	V
V_{IH}	High-Level Input Voltage	$\overline{\text{RESET}}$	1.7	—	—	V
V_{IL}	Low-Level Input Voltage	$\overline{\text{RESET}}$	—	—	0.7	V
V_{ICR}	Common-Mode Input Range	CLK, $\overline{\text{CLK}}$	0.97	—	1.53	V
$V_i(\text{PP})$	Peak-to-Peak Input Voltage	CLK, $\overline{\text{CLK}}$	360	—	—	mV
I_{OH}	High-Level Output Current		—	—	-16	mA
I_{OL}	Low-Level Output Current		—	—	16	mA
T_A	Operating Free-Air Temperature		0	—	+70	$^\circ\text{C}$

NOTE:

- The $\overline{\text{RESET}}$ input of the device must be held at V_{DD} or GND to ensure proper device operation.

TIMING REQUIREMENTS OVER RECOMMENDED OPERATING FREE-AIR TEMPERATURE RANGE

Symbol	Parameter	PC1600-PC2700		PC3200		Unit
		Min.	Max.	Min.	Max.	
CLOCK	Clock Frequency	—	200	—	220	MHz
t _w	Pulse Duration, CLK, $\overline{\text{CLK}}$ HIGH or LOW	2.5	—	2.5	—	ns
t _{ACT}	Differential Inputs Active Time ⁽¹⁾	—	22	—	22	ns
t _{INACT}	Differential Inputs Inactive Time ⁽²⁾	—	22	—	22	ns
t _{SU}	Setup Time, Fast Slew Rate ^(3,5) Data Before CLK \uparrow , CLK \downarrow	0.65	—	0.65	—	ns
		Setup Time, Slow Slew Rate ^(4,5)	0.75	—	0.75	—
t _H	Hold Time, Fast Slew Rate ^(3,5) Data Before CLK \uparrow , CLK \downarrow	0.75	—	0.65	—	ns
		Hold Time, Slow Slew Rate ^(2,5)	0.9	—	0.8	—

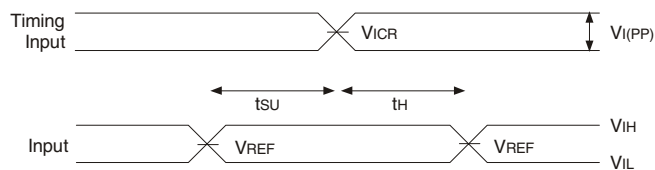
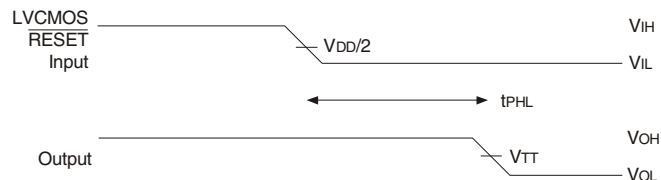
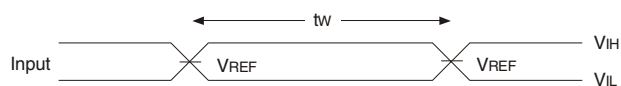
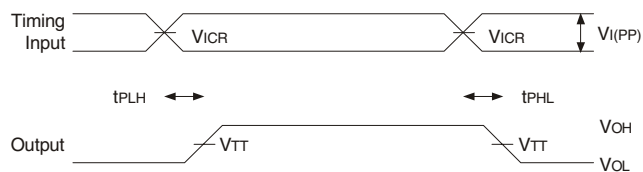
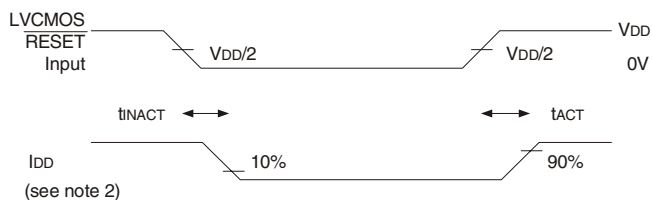
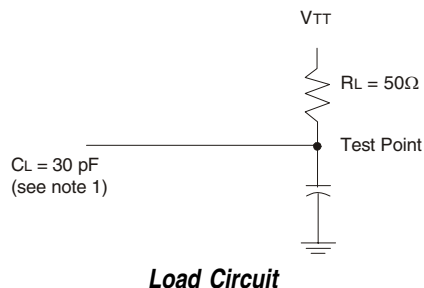
NOTES:

1. Data inputs must be low a minimum time of t_{ACT} max., after $\overline{\text{RESET}}$ is taken HIGH.
2. Data and clock inputs must be held at valid levels (not floating) a minimum time of t_{INACT} max., after $\overline{\text{RESET}}$ is taken LOW.
3. For data signal input slew rate is $\geq 1\text{V/ns}$.
4. For data signal input slew rate is $\geq 0.5\text{V/ns}$ and $< 1\text{V/ns}$.
5. CLK, $\overline{\text{CLK}}$ signal input slew rates are $\geq 1\text{V/ns}$.

SWITCHING CHARACTERISTICS OVER RECOMMENDED FREE-AIR OPERATING RANGE (UNLESS OTHERWISE NOTED)

Symbol	Parameter	Package	PC1600-PC2700		PC3200		Unit
			Min.	Max.	Min.	Max.	
f _{MAX}		TSSOP, VFQFPN	200	—	220	—	MHz
t _{PDM}	CLK and $\overline{\text{CLK}}$ to Q	TSSOP	1.1	2.4	1.1	2.2	ns
		VFQFPN	1.1	2.2	1.1	1.8	
t _{PDMS}	CLK and $\overline{\text{CLK}}$ to Q (simultaneous switching)	TSSOP	—	2.7	—	2.5	ns
		VFQFPN	—	2.5	—	((TBD))	
t _{PHL}	$\overline{\text{RESET}}$ to Q	TSSOP, VFQFPN	—	5	—	5	ns

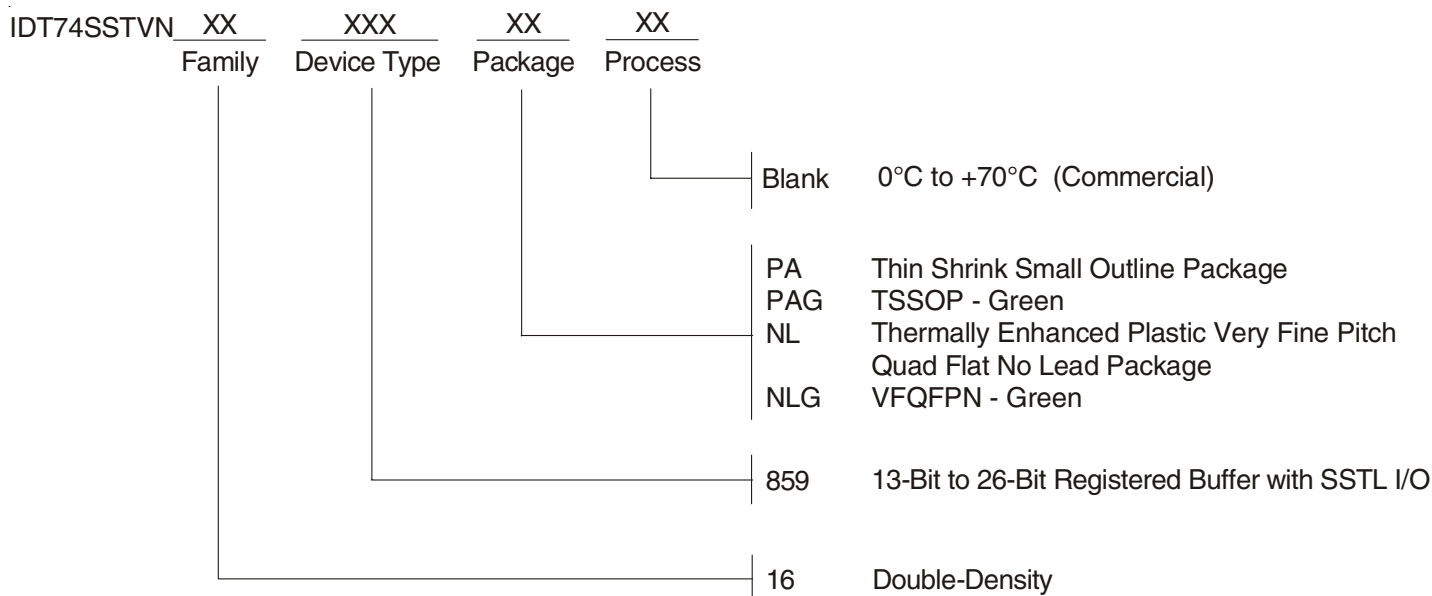
TEST CIRCUITS AND WAVEFORMS FOR PC1600 - PC2700, $V_{DD} = 2.5V \pm 0.2V$ FOR PC3200, $V_{DD} = 2.6V \pm 0.1V$



NOTES:

1. C_L includes probe and jig capacitance.
2. I_{DD} tested with clock and data inputs held at V_{DD} or GND, and $I_o = 0mA$.
3. All input pulses are supplied by generators having the following characteristics: PRR $\leq 10MHz$, $Z_o = 50\Omega$, input slew rate = $1 V/ns \pm 20\%$ (unless otherwise specified).
4. The outputs are measured one at a time with one transition per measurement.
5. $V_{TT} = V_{REF} = V_{DD}/2$
6. $V_{IH} = V_{REF} + 310mV$ (AC voltage levels) for differential inputs. $V_{IH} = V_{DD}$ for LVC MOS input.
7. $V_{IL} = V_{REF} - 310mV$ (AC voltage levels) for differential inputs. $V_{IL} = GND$ for LVC MOS input.
8. t_{PDM} is t_{PD} with one output switching. t_{PDMSS} is t_{PD} with all outputs switching.

ORDERING INFORMATION



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